



Material Content Data Sheet



Sales Product Name	TLF50281EL			Issued	1. August 2018			
MA#	MA001833538							
Package	PG-SSOP-14-3			Weight*	83.02 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.797	2.17	2.17	21651	21651
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		104	
	non noble metal	zinc	7440-66-6	0.034	0.04		415	
	non noble metal	iron	7439-89-6	0.689	0.83		8300	
wire	non noble metal	copper	7440-50-8	27.978	33.70	34.58	337002	345821
	noble metal	gold	7440-57-5	0.213	0.26	0.26	2560	2560
	encapsulation	organic material	carbon black	1333-86-4	0.100	0.12		1202
plastics	plastics	epoxy resin	-	4.591	5.53		55299	
	inorganic material	silicondioxide	60676-86-0	45.210	54.45	60.10	544576	601077
leadfinish	non noble metal	tin	7440-31-5	0.976	1.18	1.18	11758	11758
plating	noble metal	silver	7440-22-4	0.768	0.92	0.92	9246	9246
glue	plastics	epoxy resin	-	0.164	0.20		1972	
	noble metal	silver	7440-22-4	0.491	0.59	0.79	5915	7887
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com